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JC920 U.S. PTO

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

JC810 U.S. PTO
09/649827
08/29/00

Patent Application of: Edward A. Schrock et al.

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

Attorney Docket No.: 303.527US2

PATENT APPLICATION TRANSMITTAL

BOX PATENT APPLICATION

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items and information (as indicated with an "X"):

Return postcard.

DIVISIONAL of prior Patent Application No. 09/227,942 (under 37 CFR § 1.53(b)) comprising:

Specification (30 pgs, including claims numbered 1 through 57 and a 1 page Abstract).

Formal Drawing(s) (4 sheets).

Copy of signed Declaration (3 pgs) from prior application.

Copy of Power of Attorney from prior application (1 pg.)

Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*

Check in the amount of \$1,152.00 to pay the filing fee.

Prior application is assigned of record to Micron Technology, Inc.

Information Disclosure Statement (1 pg), Form 1449 (2 pgs). References NOT enclosed, cited in prior application.

Preliminary Amendment (2 pgs).

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	24 - 20 =	4	x 18 =	\$72.00
INDEPENDENT CLAIMS	8 - 3 =	5	x 78 =	\$390.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$690.00
	TOTAL			\$1,152.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

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Date of Deposit: August 29, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.